

Highly Oriented Conductive MOF Thin Film Based Schottky Diode for Self-Powered Light and Gas Detection

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Computational formulas

According to the thermionic emission theory model, the nonlinear *I-V* characteristic of Schottky diode is given by the following equation:¹

$I = I_0 [\exp(\frac{eV}{\eta k_B T}) - 1]$, where I is current across the diode, V is applied voltage, T is absolute temperature, k_B is the Boltzmann's constant, η is the ideality factor which can be expressed as $\eta = (\frac{e}{k_B T}) (\frac{dV}{dlnI})$. I_0 is reversed saturated current and can be described by following equation : $I_0 = A^* T^2 \exp(\frac{e\Phi_B}{k_B T})$, where A^* is the effective Richardson constant ($\approx 252 \text{ A K}^{-2}$ for n-type silicon)² and Φ_B is the zero-bias and Φ_B is the zero-bias Schottky-barrier height. Φ_B can be calculated from short-circuit current. Figure S13 are semi-logarithm plots of current-voltage curves for Ag/n-Si/Al and Ag/M₃(C₁₈H₆X₆)₂/n-Si/Al. The large short-circuit current in Ag/n-Si mainly results from lower Schottky barrier height between silver electrode and n-type silicon. After EC-MOFs thin film insertion, short-circuit current significantly decreases from 10^{-5} A for Ag/n-Si to 10^{-10} A for Ag/Cu₃(C₁₈H₆O₆)₂/n-Si. The series resistance R_S can be extracted by the following equation:³

$$\frac{dV}{dlnI} = \frac{\eta k_B T}{e} + R_S I.$$

Computational formulas for photodetector parameters:

Responsitivity $R_\lambda = \frac{I_{photo}}{P_S S}$, where I_{photo} is the photocurrent at zero voltage, P is incident light intensity, S is active device area.

External quantum efficiency EQE = $\frac{hcR_\lambda}{e\lambda}$, where h , c and e are Plank constant, speed of light and charge of electron, respectively.

Detectivity $D^* = \frac{\sqrt{S}R_\lambda}{\sqrt{2e}I_{dark}}$, where I_{dark} is the dark current at zero voltage.

The rise and fall time can also be obtained which determined from the time interval for the photocurrent rising (decaying) from 10% (90%) to 90% (10%) of its peak value, respectively.

Impedance Spectroscopy Measurement

The impedance spectroscopy measurement was measured over the range of 1 Hz to 1 MHz with an oscillation amplitude of 10 mV and 0 V DC under 450 nm light illumination. The impedance spectroscopy of Ag/Cu₃(C₁₈H₆(NH)₆)₂/n-Si/Al device and fitted equivalent circuit are shown in Figure S15. R_1 , R_2 and C_1 are series resistance, recombination resistance and the chemical capacitance, respectively. The carrier

lifetime is the product of R_2 and C_1 .¹⁷ Carrier lifetime of Ag/Cu₃(C₁₈H₆(NH)₆)₂/n-Si/Al device is 0.12 μ s at 450 nm light illumination. Carrier diffusion length (L_D) determined by $L_D = (k_B T \mu \tau_r / e)^{1/2}$ is 27.3 nm in the Cu₃(C₁₈H₆(NH)₆)₂ film, where k_B , T , μ , τ_r and e are the Boltzmann constant, temperature, carrier mobility, carrier lifetime and elementary charge, respectively.⁴ The carrier mobility of Cu₃(C₁₈H₆(NH)₆)₂ film is 0.02 cm²/V/s according to Hall measurement.

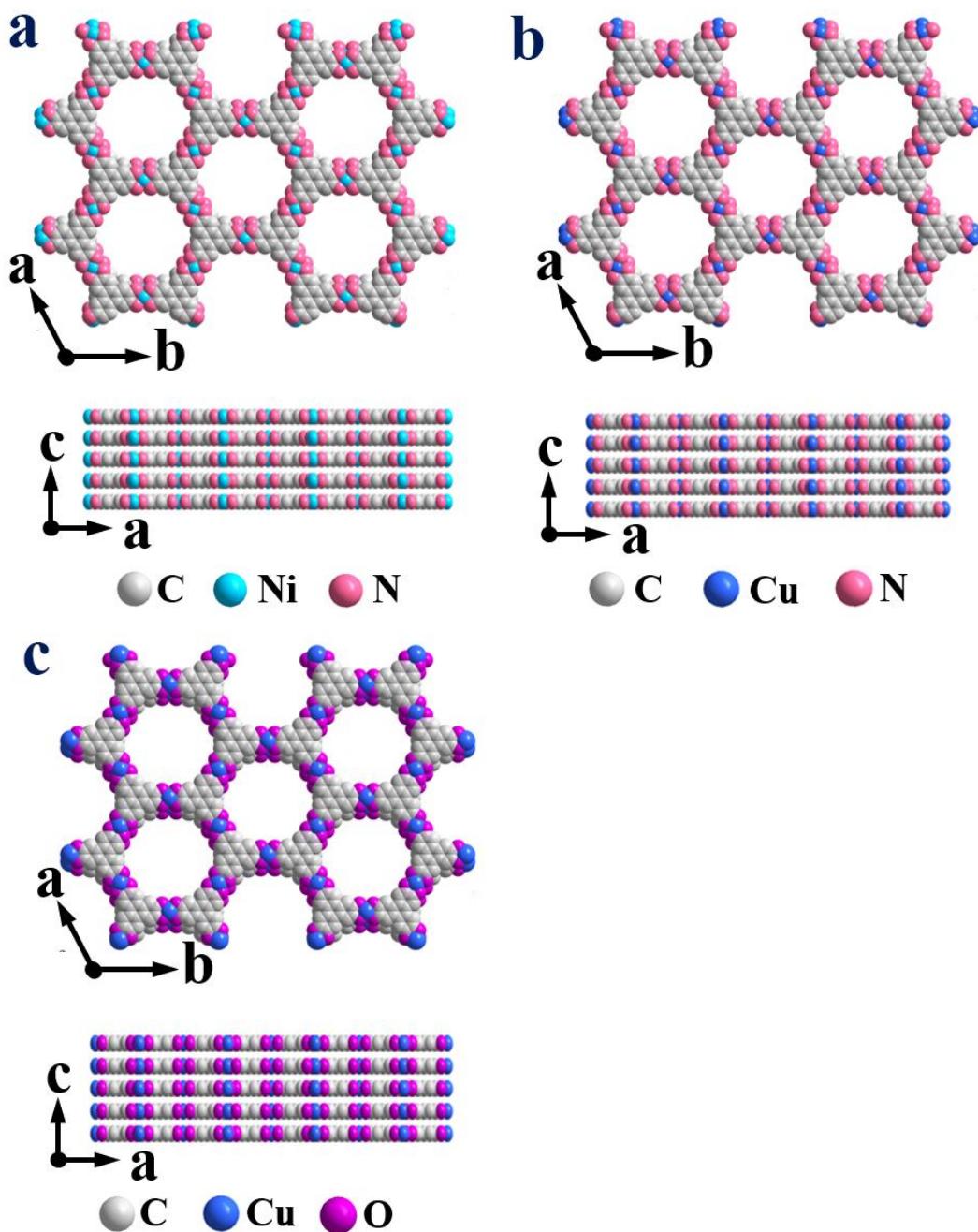


Figure S1. Crystalline structure of (a) $\text{Ni}_3(\text{C}_{18}\text{H}_6\text{(NH)}_6)_2$; (b) $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{(NH)}_6)_2$ and (c) $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$.

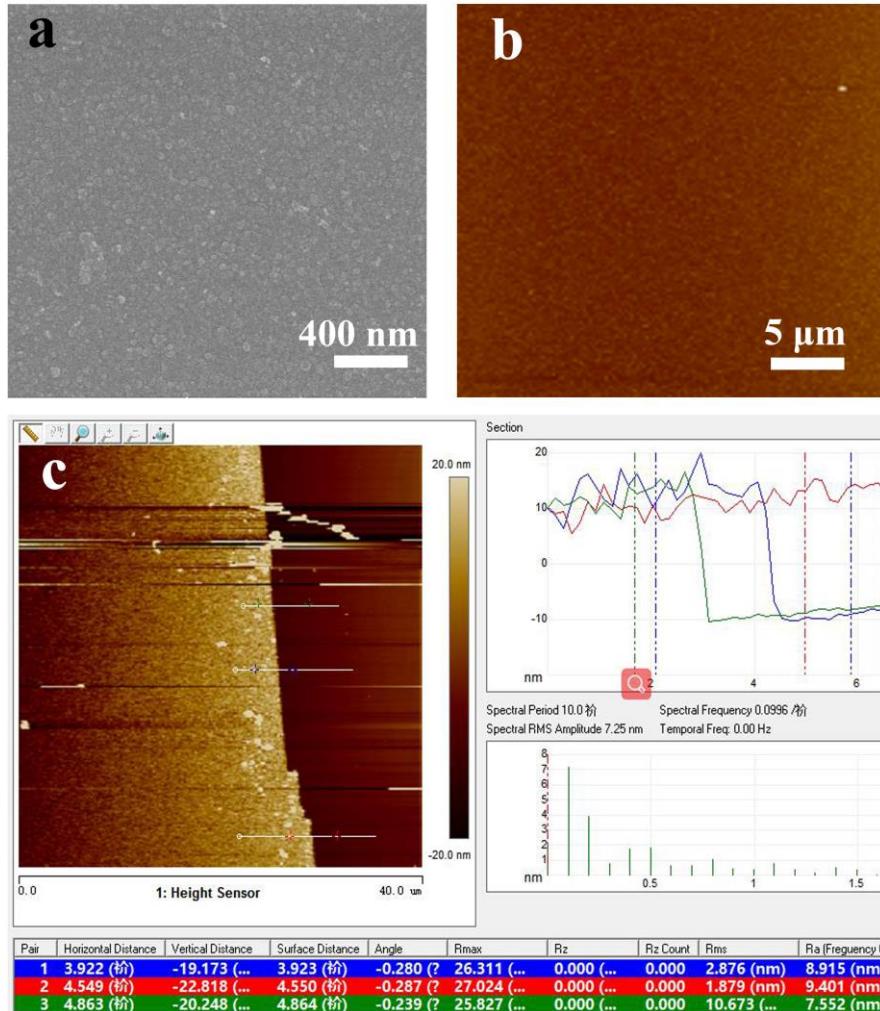


Figure S2. (a) Top views HR-SEM; (b) Top view AFM image; (c) AFM image of the edge of $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$ -20nm thin film.

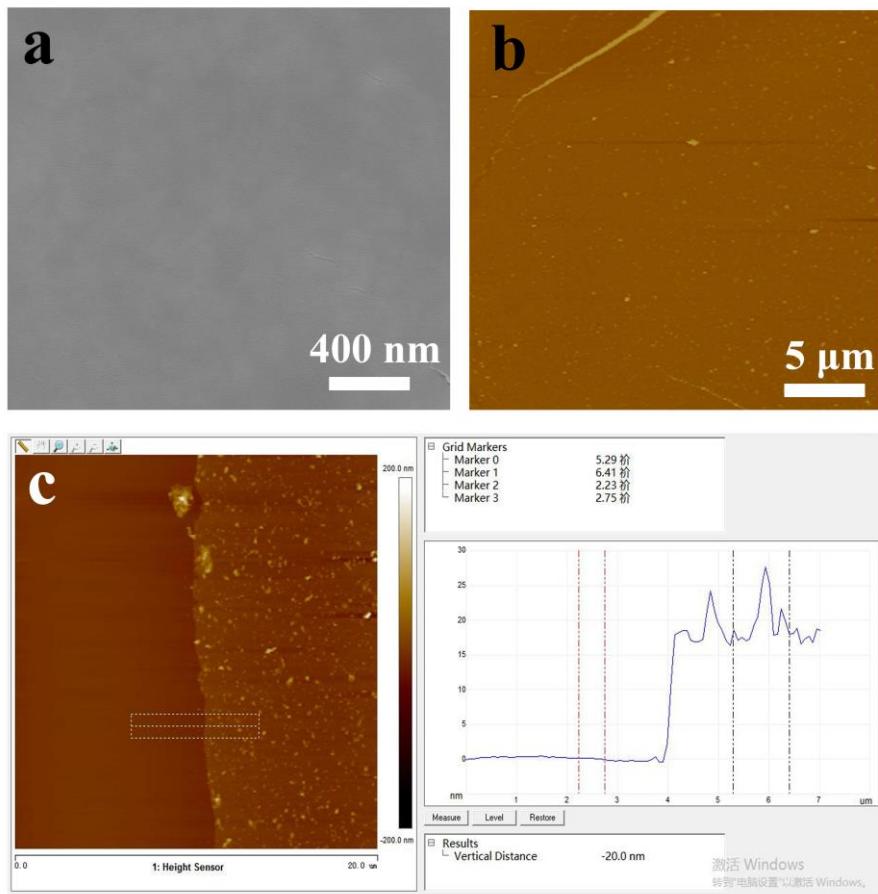


Figure S3. (a) Top views HR-SEM; (b) Top view AFM image; (c) AFM image of the edge of $\text{Ni}_3(\text{C}_{18}\text{H}_6\text{NH})_6)_2$ -20nm thin film.

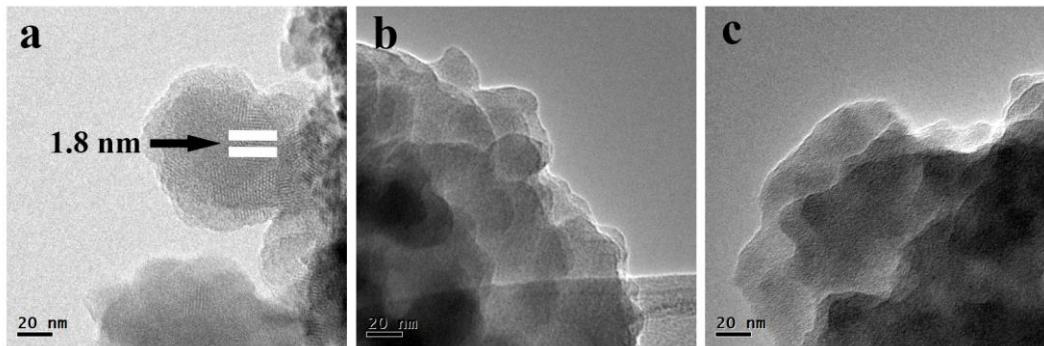


Figure S4. HR-TEM images of (a) $\text{Ni}_3(\text{C}_{18}\text{H}_6\text{NH})_6)_2$, (b) $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{NH})_6)_2$ and (c) $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$, respectively.

$\text{Ni}_3(\text{C}_{18}\text{H}_6\text{NH})_6)_2$ thin film possess obvious lattice fringes with lattice spacing of 1.8 nm which is consistent with the periodic arrangement of HITP interconnected by nickel center. $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{NH})_6)_2$ and $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$ thin film prepared by layer-by-layer method are distinct lamellar film.

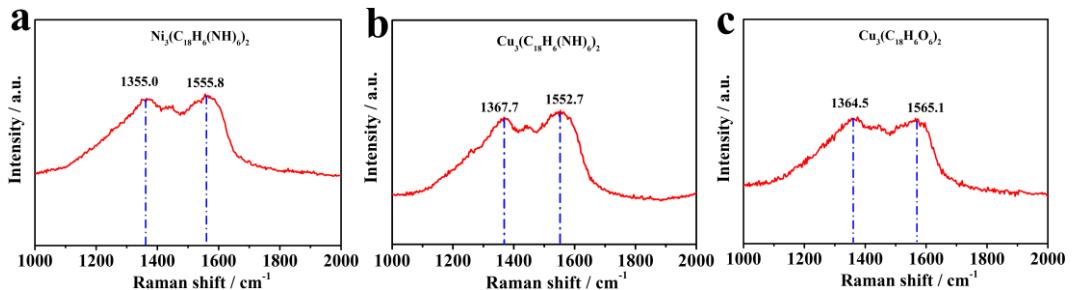


Figure S5. Raman spectra of (a) $\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$, (b) $\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ and (c) $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$ film.

Raman characterization revealed three peaks at about 1355.0, 1367.7 and 1364.5 cm⁻¹ in $\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$, $\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ and $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$, respectively, reminiscent of the D bands of 2D graphitic materials. Correspondingly, other three peaks at about 1555.8, 1552.7 and 1565.1 cm⁻¹ in $\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$, $\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ and $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$, respectively, reminiscent of the G bands of 2D graphitic materials.⁵

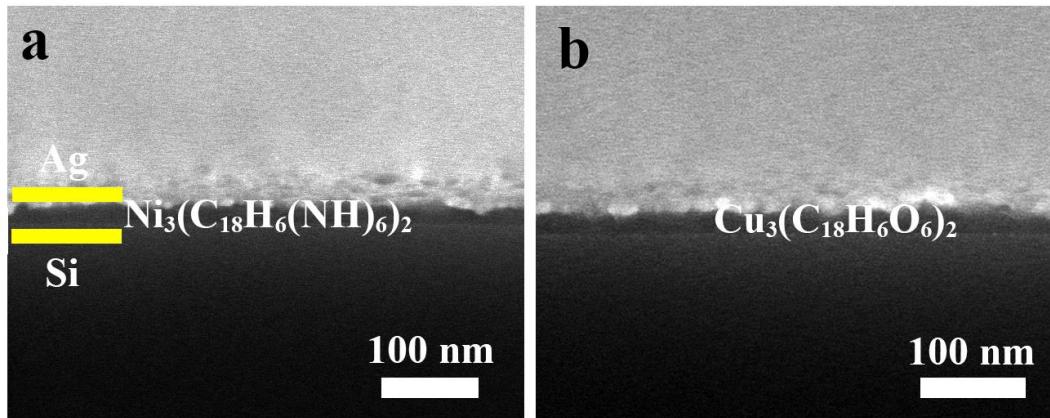


Figure S6. HR-SEM cross-section views of (a) Ag/ $\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ -20nm /n-Si; (b) Ag/ $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$ -20nm /n-Si device.

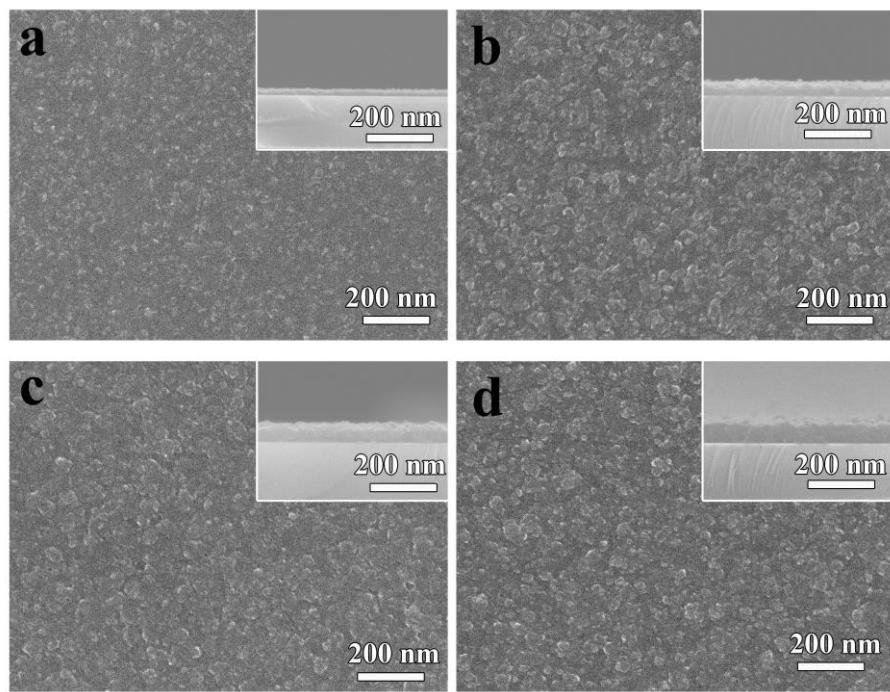


Figure S7. Top views HR-SEM of $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{NH})_6$ 2-xnm thin film in which x are (a) 40; (b) 60; (c) 80 and (d) 100 (insets are cross sectional views).

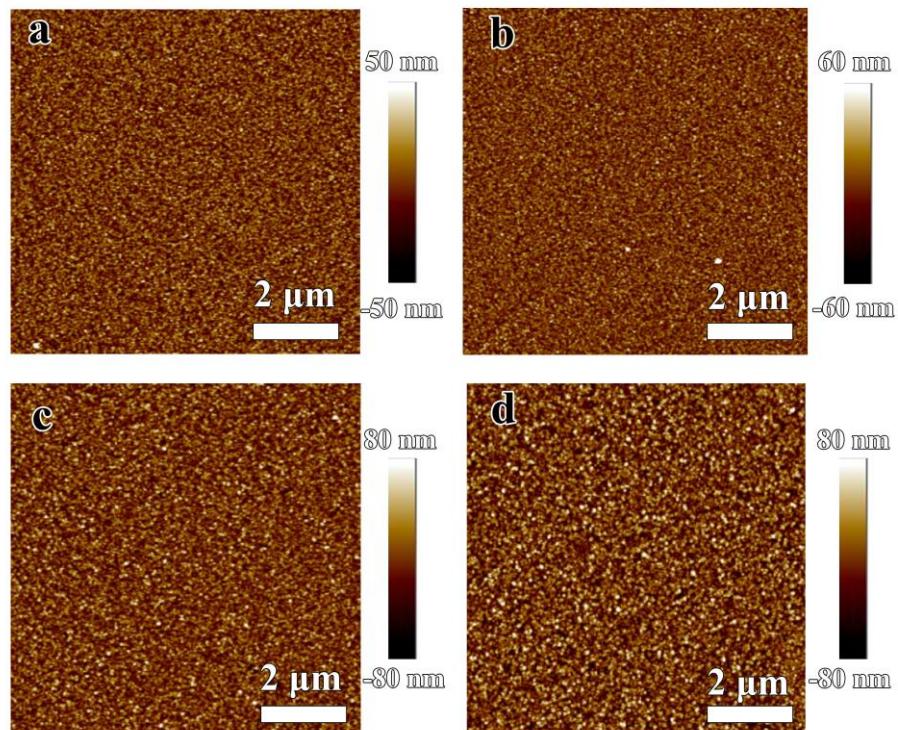


Figure S8. Top view AFM images of $\text{Cu}_3(\text{C}_{18}\text{H}_6\text{NH})_6$ 2-xnm thin film in which x are (a) 40; (b) 60; (c) 80 and (d) 100, respectively.

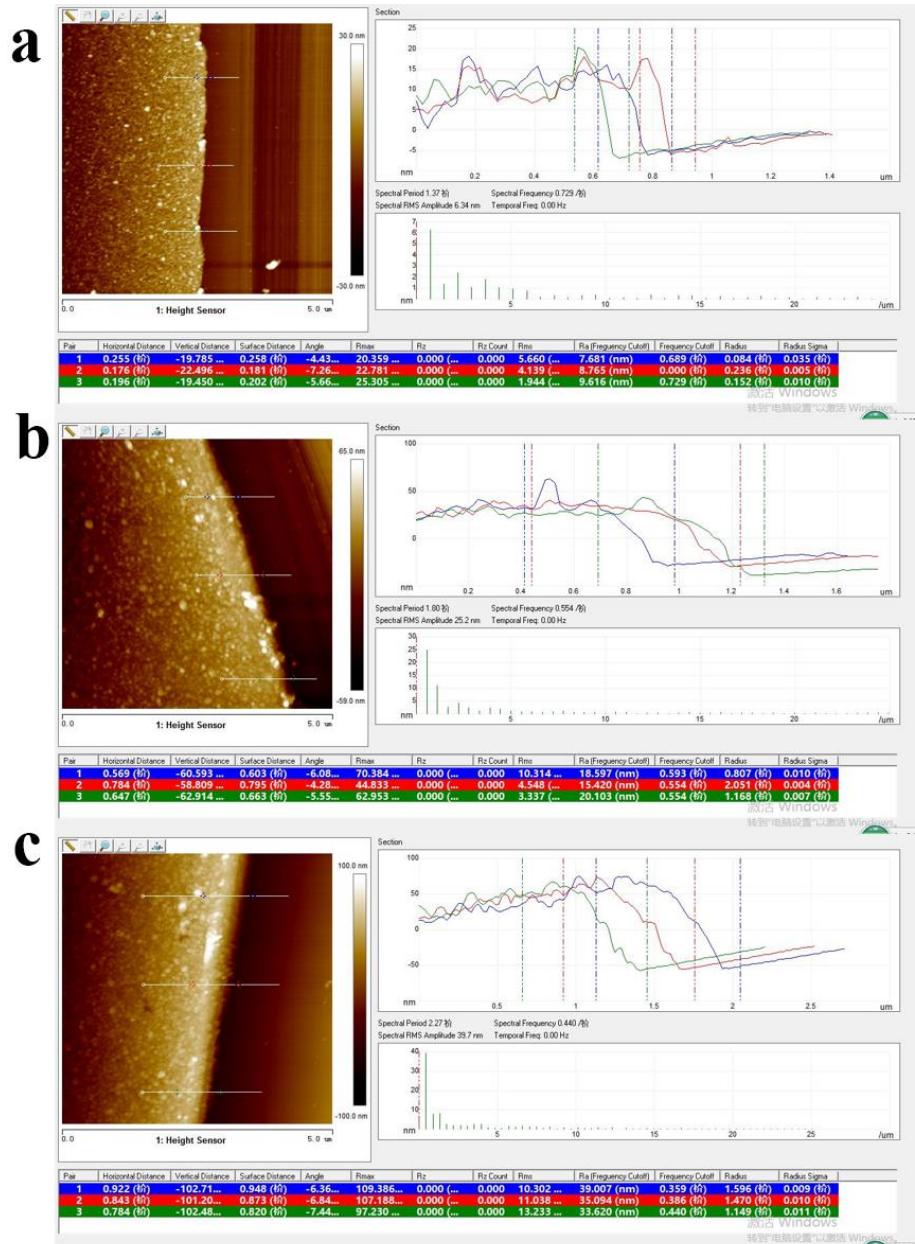


Figure S9. AFM images of the edge of $\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2\text{-xnm}$ thin film with (a) 20nm; (b) 60nm and (c)100nm, respectively.

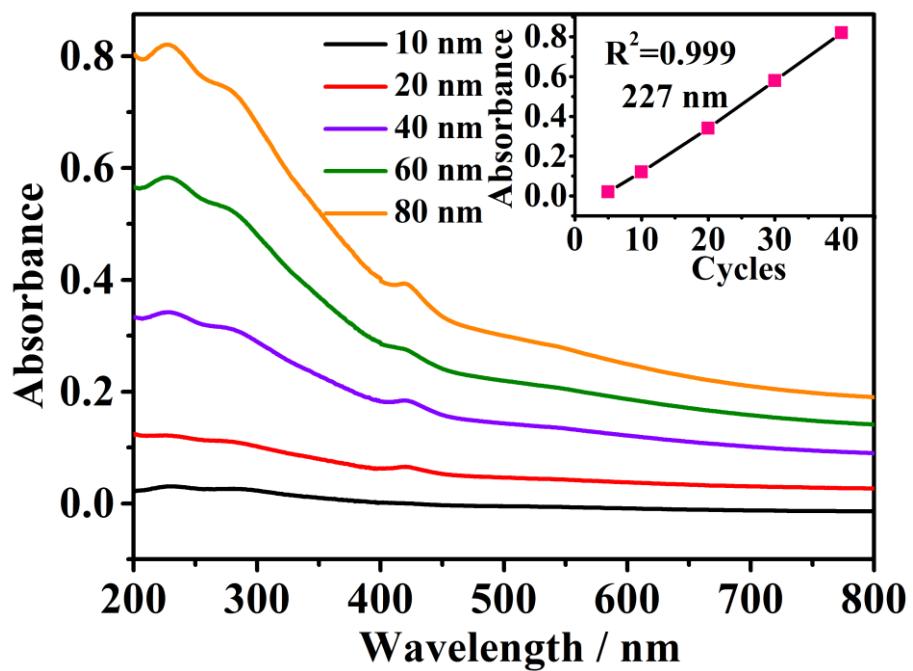


Figure S10. UV-Vis absorbance spectra of Cu₃(C₁₈H₆(NH)₆)₂-xnm (inset is cycle-dependent intensity of absorbance at 227 nm).

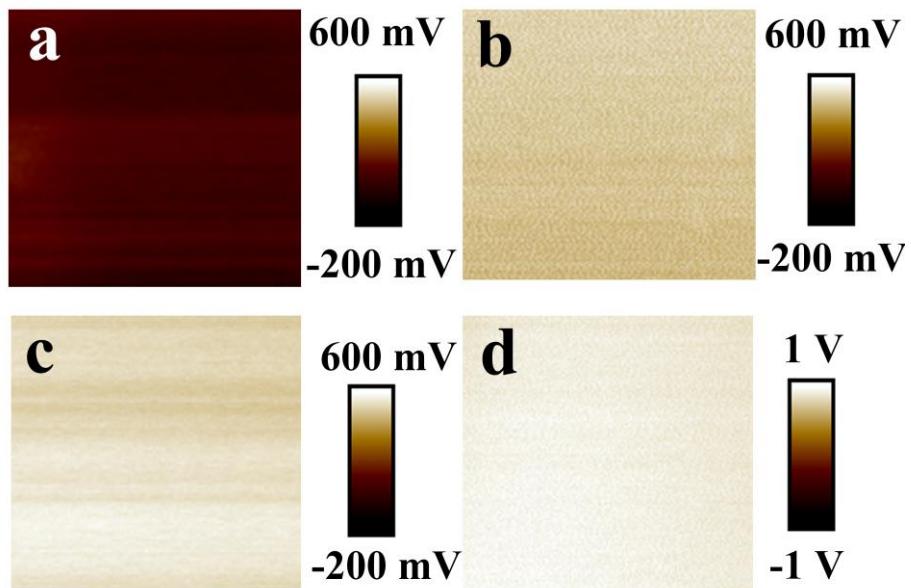


Figure S11. KPFM patterns of (a)Ag; (b) Ni₃(C₁₈H₆(NH)₆)₂-20nm; (c) Cu₃(C₁₈H₆(NH)₆)₂-20nm and (d) Cu₃(C₁₈H₆O₆)₂-20nm thin film.

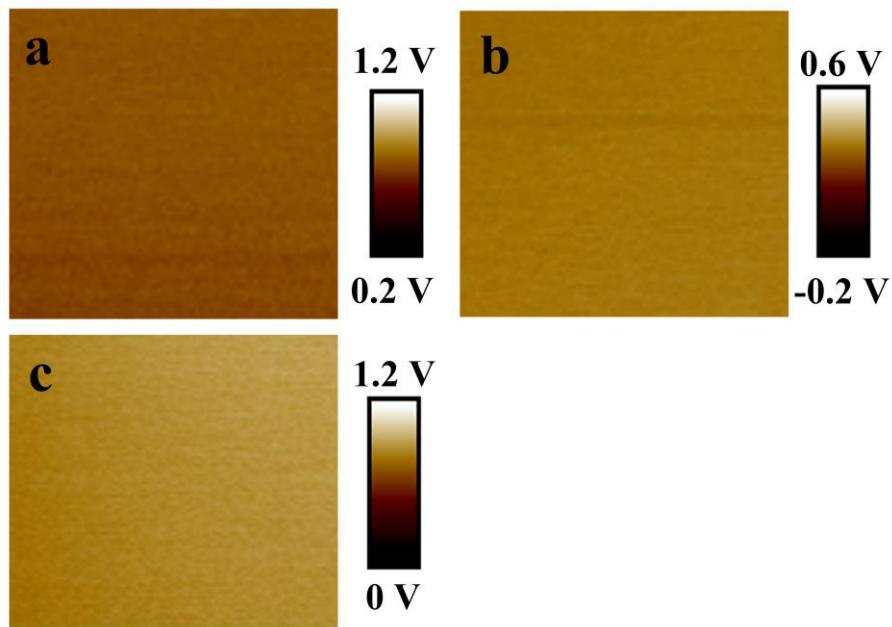


Figure S12. KPFM of (a) $\text{Ag}/\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ -20nm; (b) $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ -20nm and (c) $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2$ -20nm.

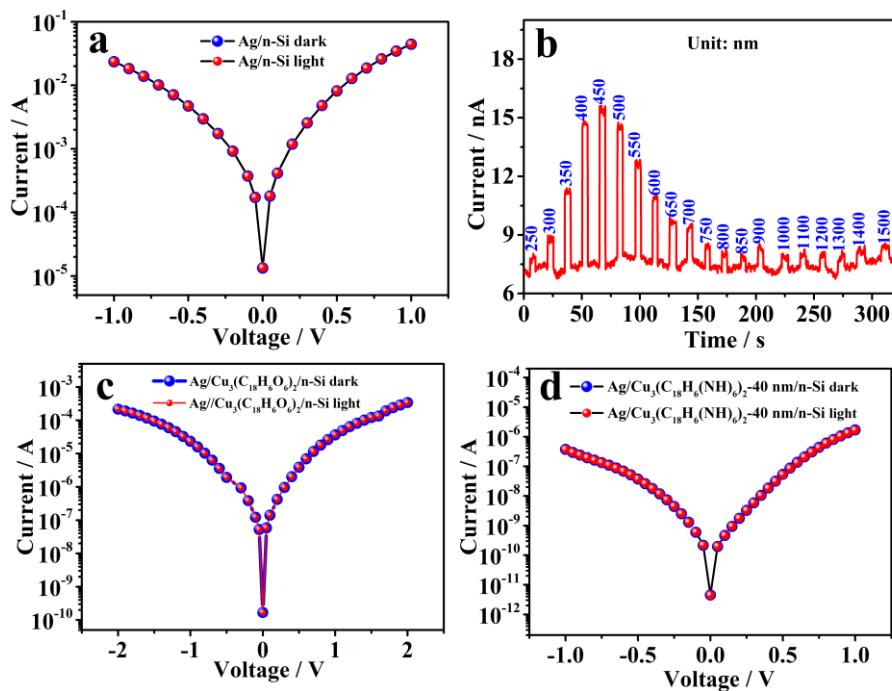


Figure S13. (a) Semi-logarithm plot of current-voltage for $\text{Ag}/\text{n-Si}/\text{Al}$ under illumination and dark condition; (b) Time-dependent photoresponse of $\text{Ag}/\text{Ni}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si}$ under different wavelength light; (c) Semi-logarithm plot of current-voltage for $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6\text{O}_6)_2/\text{n-Si}$ under illumination and dark condition; (d) Semi-logarithm plot of current-voltage for $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2$ -40 nm/n-Si under illumination and dark condition.

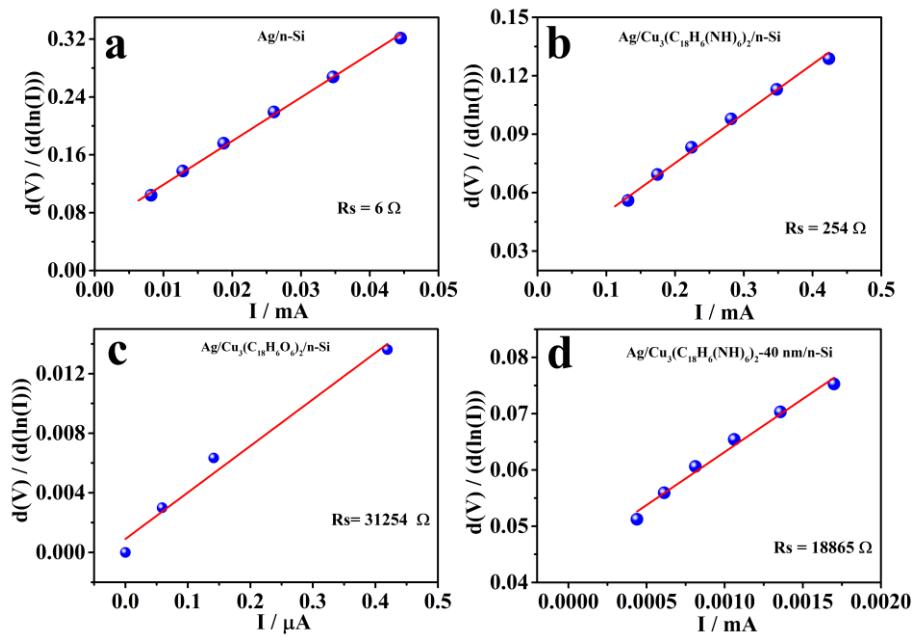


Figure S14. $dV/d\ln I$ versus I plot of (a) Ag/n-Si, (b) Ag/Cu₃(C₁₈H₆(NH)₆)₂/n-Si; (c) Ag/Ni₃(C₁₈H₆O₆)₂/n-Si and (d) Ag/Cu₃(C₁₈H₆(NH)₆)₂-40nm/n-Si, respectively.

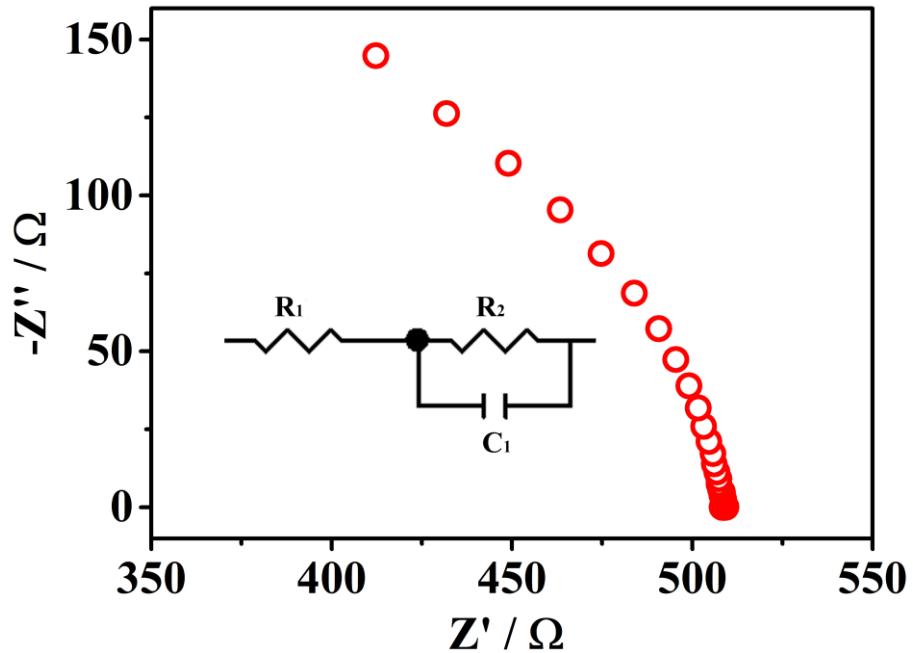


Figure S15. Impedance spectroscopies of Ag/Cu₃(C₁₈H₆(NH)₆)₂/n-Si/Al under 450nm light illumination (inset is fitted equivalent circuit).

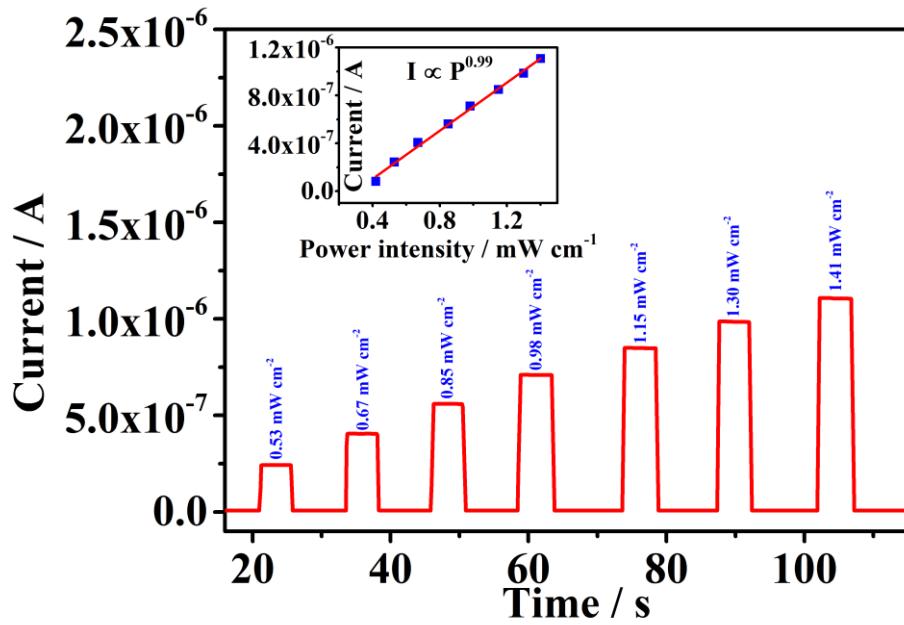


Figure S16. Photo response of $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si}$ under 450nm light illumination with different intensity, the inset shows the photocurrent variation with light intensity fitted by power law.

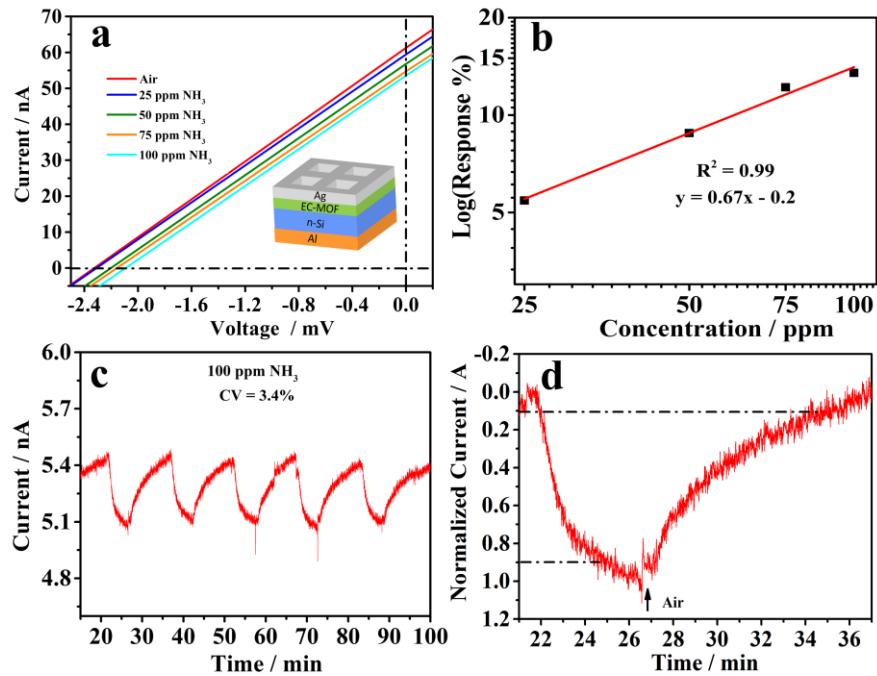


Figure S17. (a) Partial current-voltage characteristics of $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si/Al}$ diode in air and NH_3 atmosphere irradiating with 450 nm visible light; (b) Linear fitted log-log plots of response and NH_3 concentration for $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si/Al}$; (c) Five cycles response-recovery curves of $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si/Al}$ toward 100 ppm NH_3 ; (d) Normalized response-recovery curves of $\text{Ag}/\text{Cu}_3(\text{C}_{18}\text{H}_6(\text{NH})_6)_2/\text{n-Si/Al}$ to 100 ppm NH_3 .

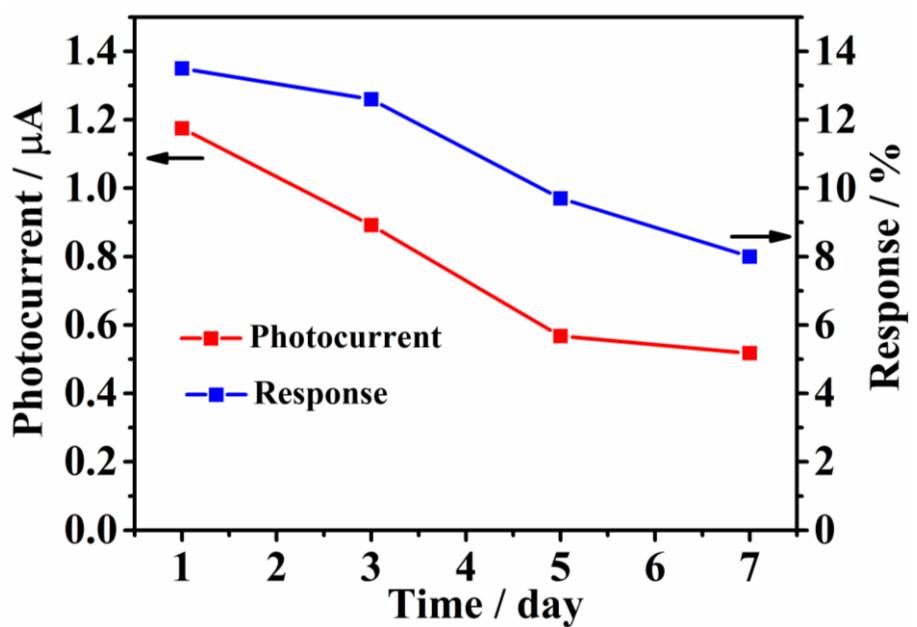


Figure S18. Long-term stability of Ag/Cu₃(C₁₈H₆(NH)₆)₂/n-Si for 7 days.

Table S1. Comparison of the key parameters for self-powered photoconductor

Materials	Device type	On/off ratio	Responsivity [mA W ⁻¹]	Detectivity [Jones]	Rise/fall time	Response range (nm)	EQE (%)	Ref.
MoS₂/h-BN/graphene	vander waals	10 ³	360	6.7×10^{10}		532	80	1 ⁶
MoS₂/p-Si	heterojunction	10 ³	253	10^9	84/136 ms	532		2 ⁷
PEDOT:PSS/Si	heterojunction	10 ⁵	37.8	4.1×10^{11}	2/172 μ s	300-1100	80	3 ⁸
a-C/Si	heterojunction	10 ²	292.5	2.9×10^{13}	8.3/33.1 μ s	300-1100		4 ⁹
GaN//Si	heterojunction	10 ⁴	210	7.5×10^{12}	9/8 ms	325-825	50	5 ¹⁰
Perovskite/TiO₂/Si	heterojunction	11 ⁶		6×10^{12}	50/150 ms	350-1150		6 ¹¹
Te/TiO₂	heterojunction	100	84	3.7×10^9	0.77/1.49 s	300-500		7 ¹²
PEDOT:PSS/P-TPD/QDs/ZnO	heterojunction	10 ⁶	45	2.6×10^{12}	40 ms	300-900		8 ¹³
p-Si/n-CdS	p-n junction		5.9	1.3×10^{12}	245/277 μ s	325-1550		9 ¹⁴
Pd-MoS₂/Si	p-n junction	10 ²	654	10^{14}	2.1/173.8 μ s	300-1100	35	10 ¹⁵
n-Si/p-NiO	p-n junction	10 ²	430	1.5×10^{10}	<30 ms)	350-600	20	11 ¹⁶
Ag-p-NiO/n-rGO	p-n junction	10 ³	72	3.95×10^{12}	0.80/0.84 s	365	24.5	12 ¹⁷
ZnO-Al₂O₃-Co₃O₄	p-i-n junction	≈4	21.8	4.12×10^{12}	6 s	vis		13 ¹⁸
Si/TiO₂/P₃HT	p-i-n junction	10 ⁴	590(920)	1.38×10^{14}	84/153 μ s	300-1100		14 ¹⁹
Graphene/ZnO/Si	Schottky	10 ⁴	500		280/540 μ s	400-1000		15 ²⁰
Graphene/GaAs	Schottky		1.54		71/194 μ s	532		16 ¹
Graphene/MoO₃/Si	Schottky	≈10	400	5.4×10^{12}		300-1100	80	17 ²
(P3HT)/MoO₃/Ag	Schottky	10 ⁴		6.03×10^{12}	26.9 μ s	300-800	6.6	18 ²¹
CdS:Ga /Au	Schottky	10 ³	8000		95/290 μ s	350-650		19 ²²
SiNWs/Cu	Schottky	10 ⁴	335	2.9×10^{12}	3.6/14 μ s	460-1100		20 ²³
SiNWs/Ag NWs(5V)	Schottky	5			0.43/0.58 ms	400-1000		21 ²⁴
Cu/p-Si	Schottky	≈10				White light		22 ²⁵
Au/SnO₂ NW	Schottky	6.08	0.36 (370)	3.02×10^9	0.72/1.78 s	300-600		23 ²⁶
Au-Si-Ti	Schottky		80			400-1000	10.3	24 ²⁷
TiO₂/Ag NWs	Schottky	1700	32.5	6×10^9	44 ns/1.9 μ s	200-400	16	25 ²⁸
Ag/MOF/Si	Schottky	10 ³	300	3.2×10^{11}	7/30 ms	250-1500	84	This work

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